

FIG. 1(A)

FORMING STEP OF AMORPHOUS SEMICONDUCTOR FILM

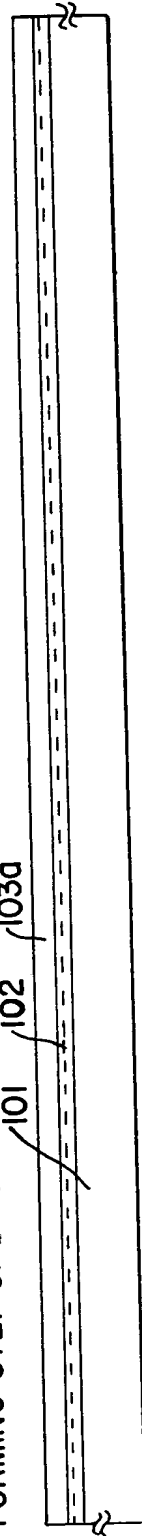


FIG. 1(B)

CRYSTALLIZATION STEP

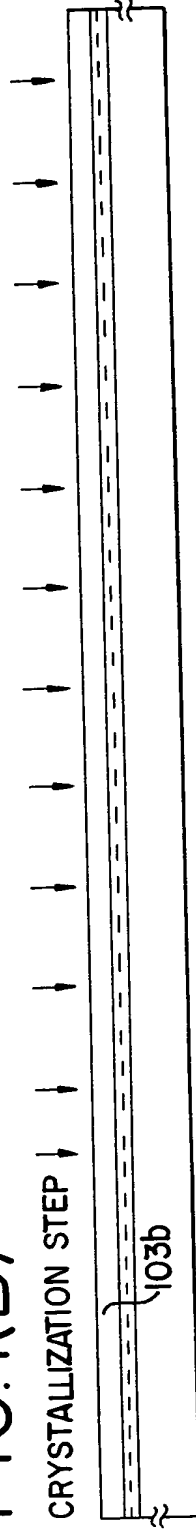


FIG. 1(C)

FORMING STEP OF MASK LAYER

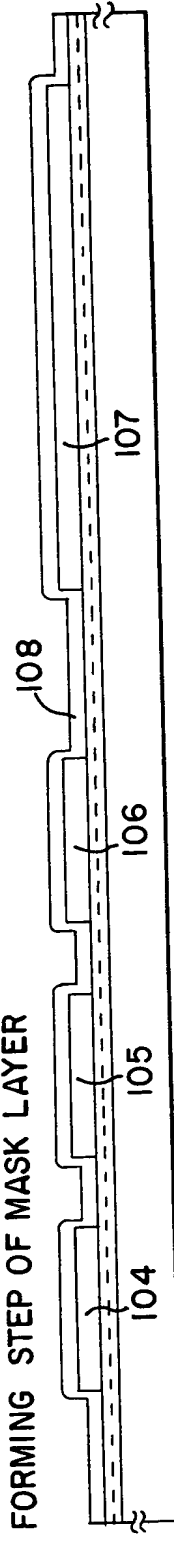


FIG. 1(D)

CHANNEL DOPING STEP

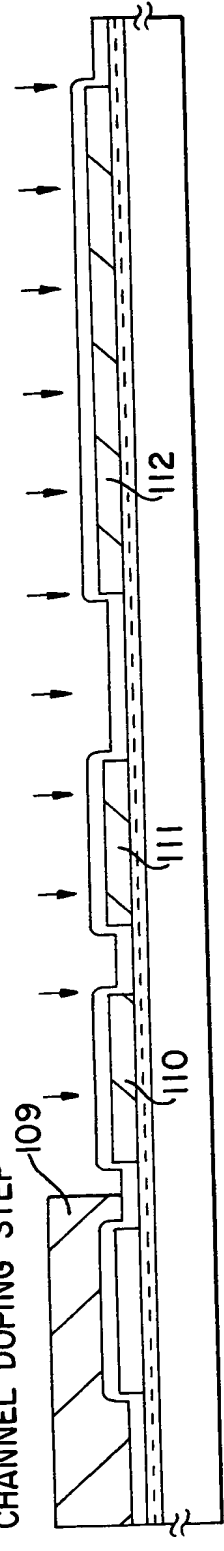


FIG. 2(A)

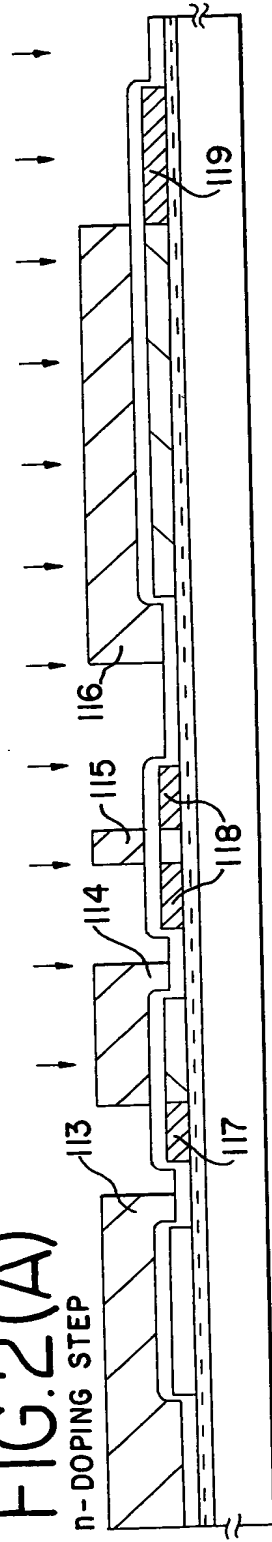


FIG. 2(B)

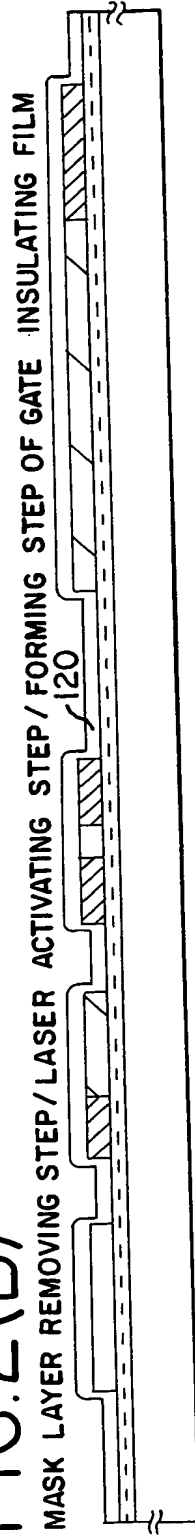


FIG. 2(C)

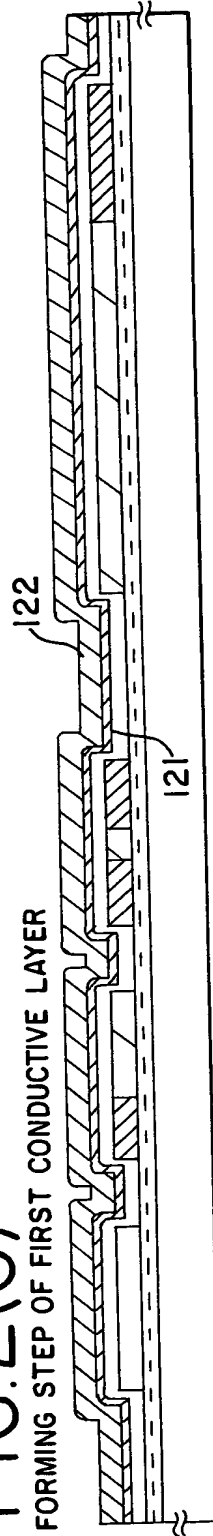


FIG. 2(D)

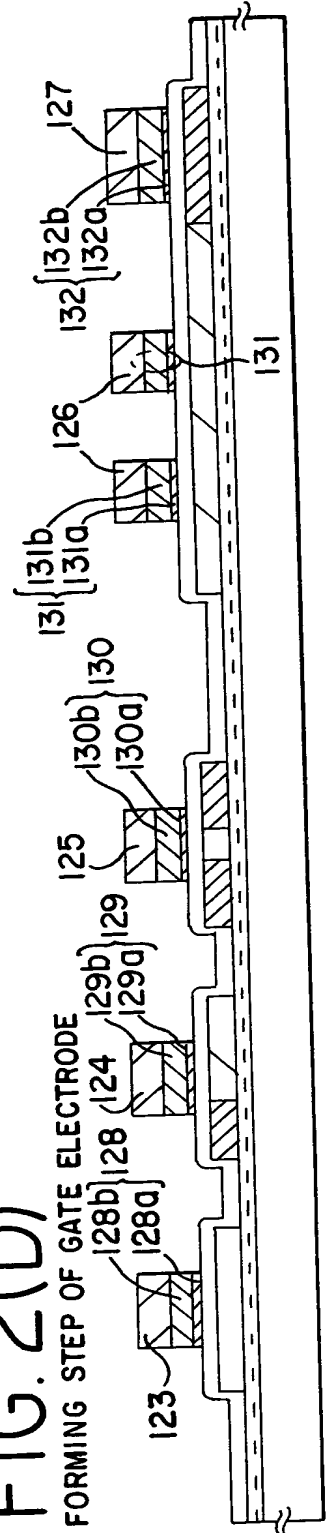


FIG. 3(A)

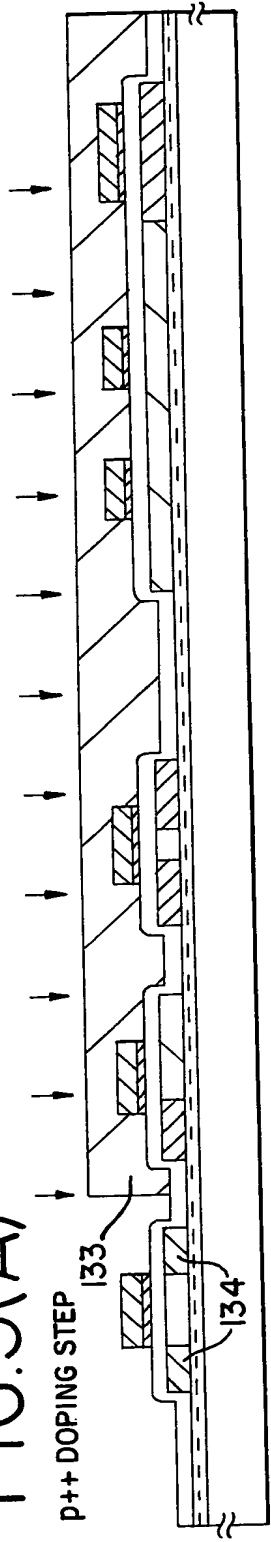


FIG. 3(B)

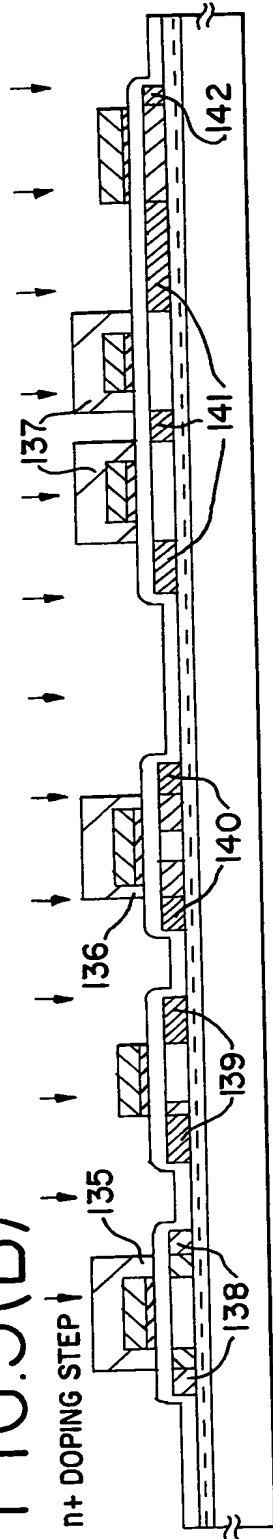


FIG. 3(C)

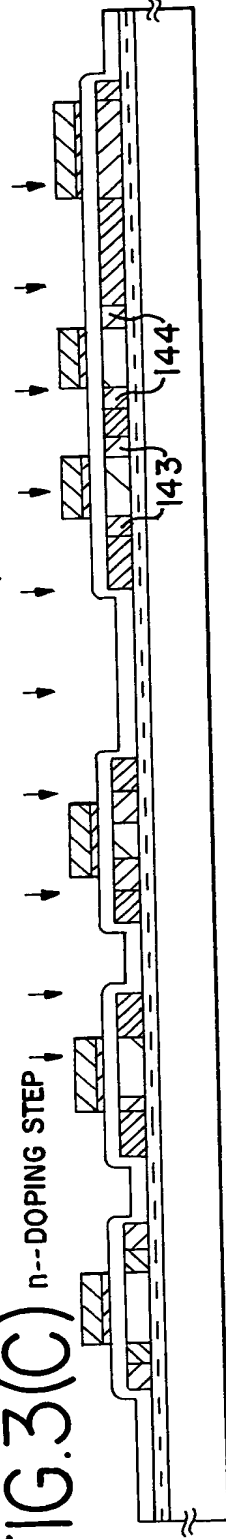
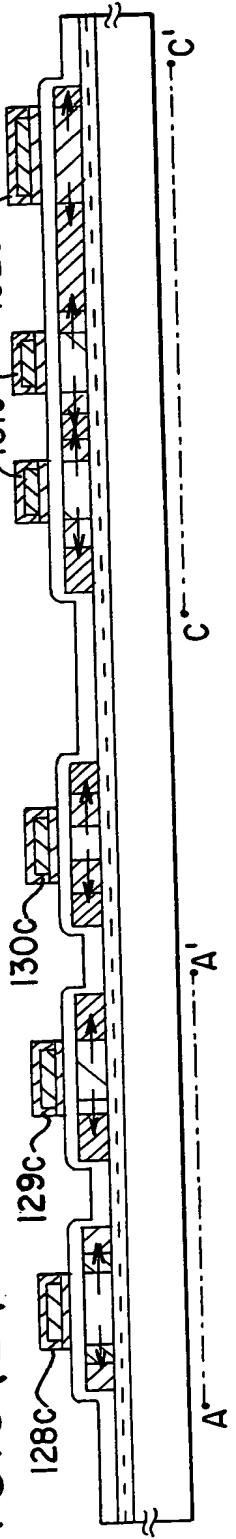


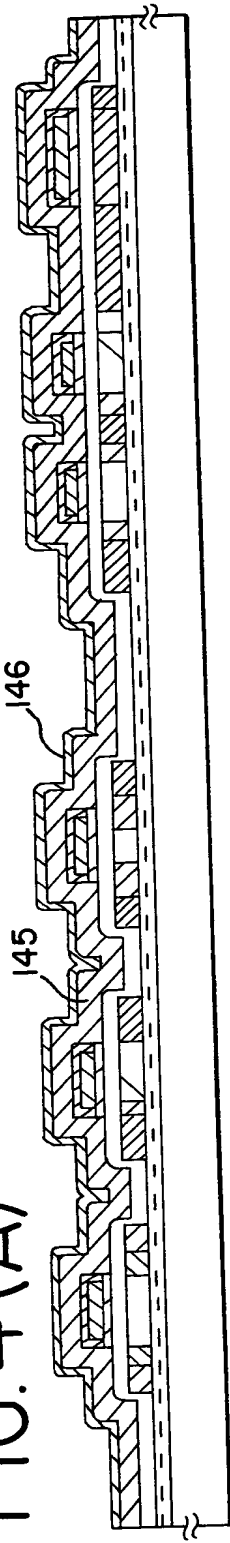
FIG. 3(D)

ACTIVATING (GETTERING) STEP / NITROGENATION STEP / HYDROGENATION STEP



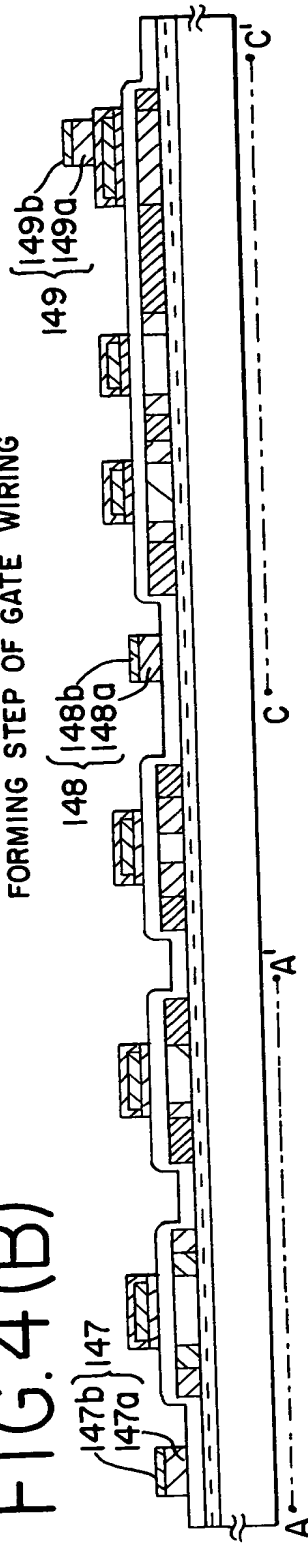
FORMING STEP OF SECOND CONDUCTIVE LAYER

FIG. 4(A)



FORMING STEP OF GATE WIRING

FIG. 4(B)



FORMING STEP OF INTERLAYER INSULATING FILM / FORMING STEP OF CONTACT HOLE / FORMING STEP OF WIRING / FORMING STEP OF PASSIVATION FILM

FIG. 4(C)

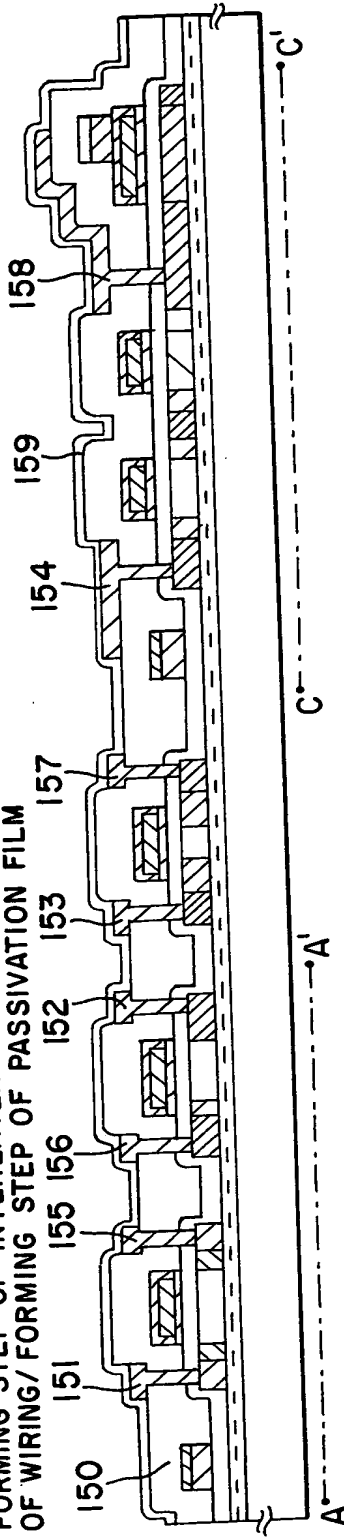


FIG. 5

FORMING STEP OF RESIN FILM / FORMING STEP OF CONTACT HOLE / FORMING STEP OF PIXEL ELECTRODE

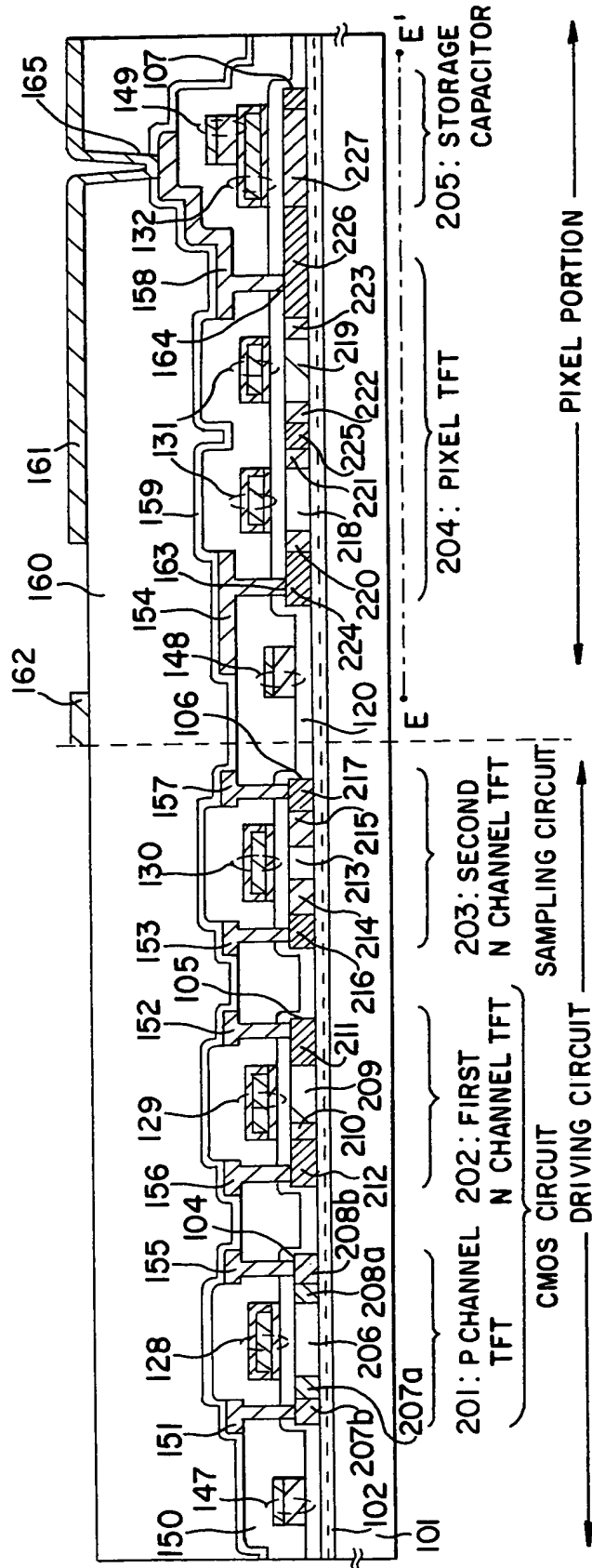


FIG.6(A)

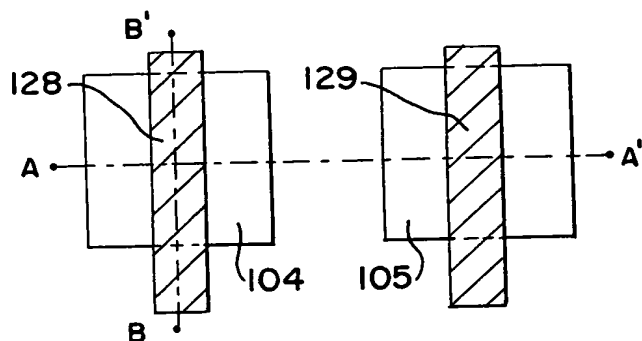


FIG.6(B)

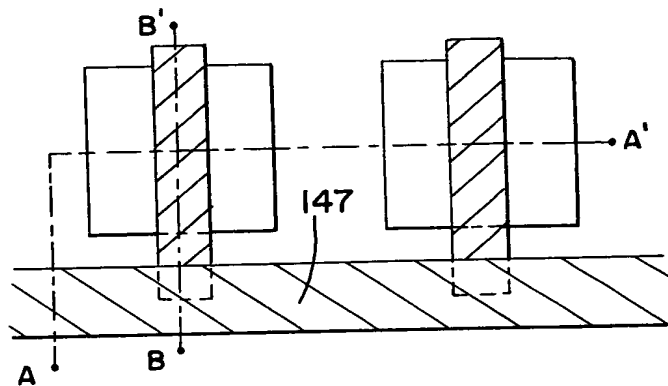


FIG.6(C)

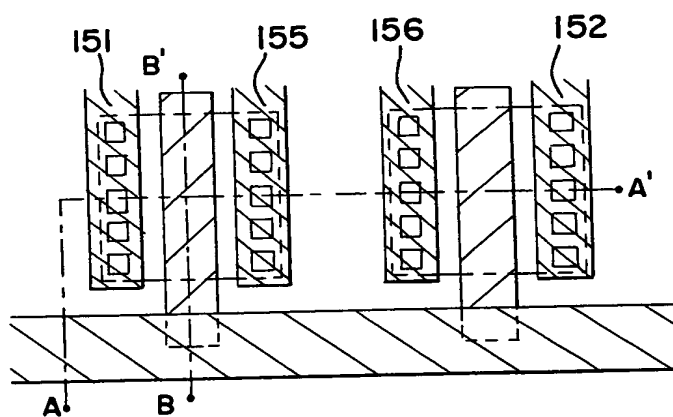


FIG.7(A)

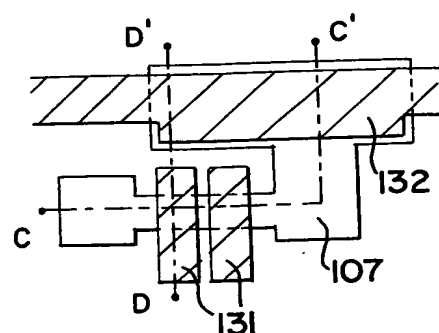


FIG.7(B)

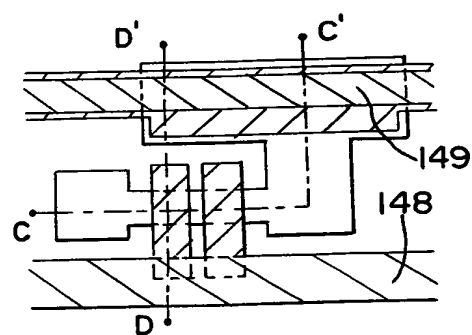


FIG.7(C)

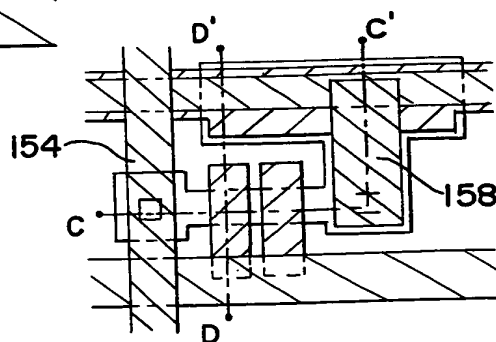


FIG.8(A)

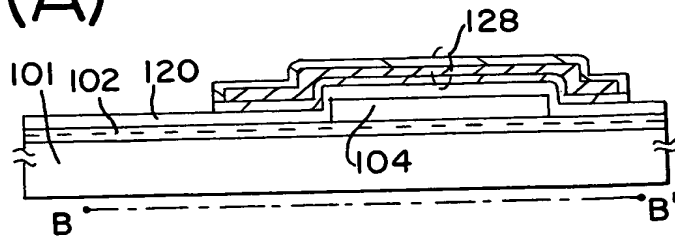


FIG.8(B)

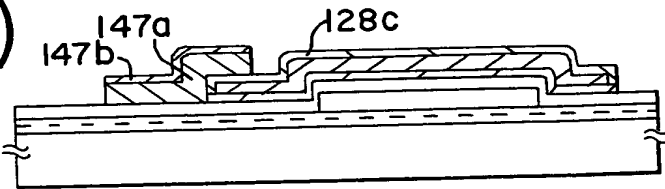


FIG. 8(C)

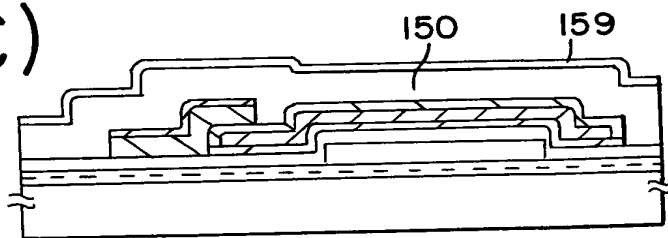


FIG.9(A)

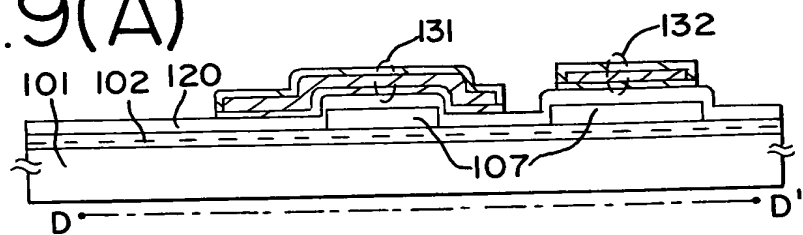


FIG.9(B)

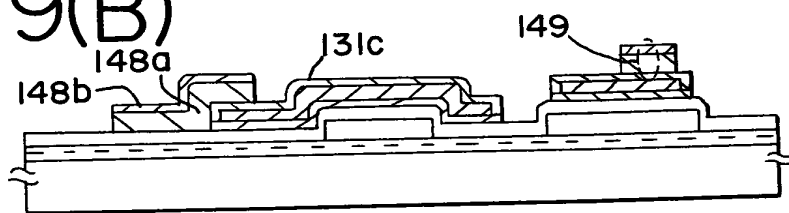


FIG. 9(C)

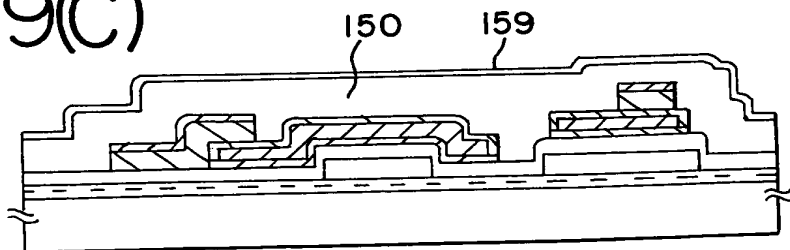


FIG. 10

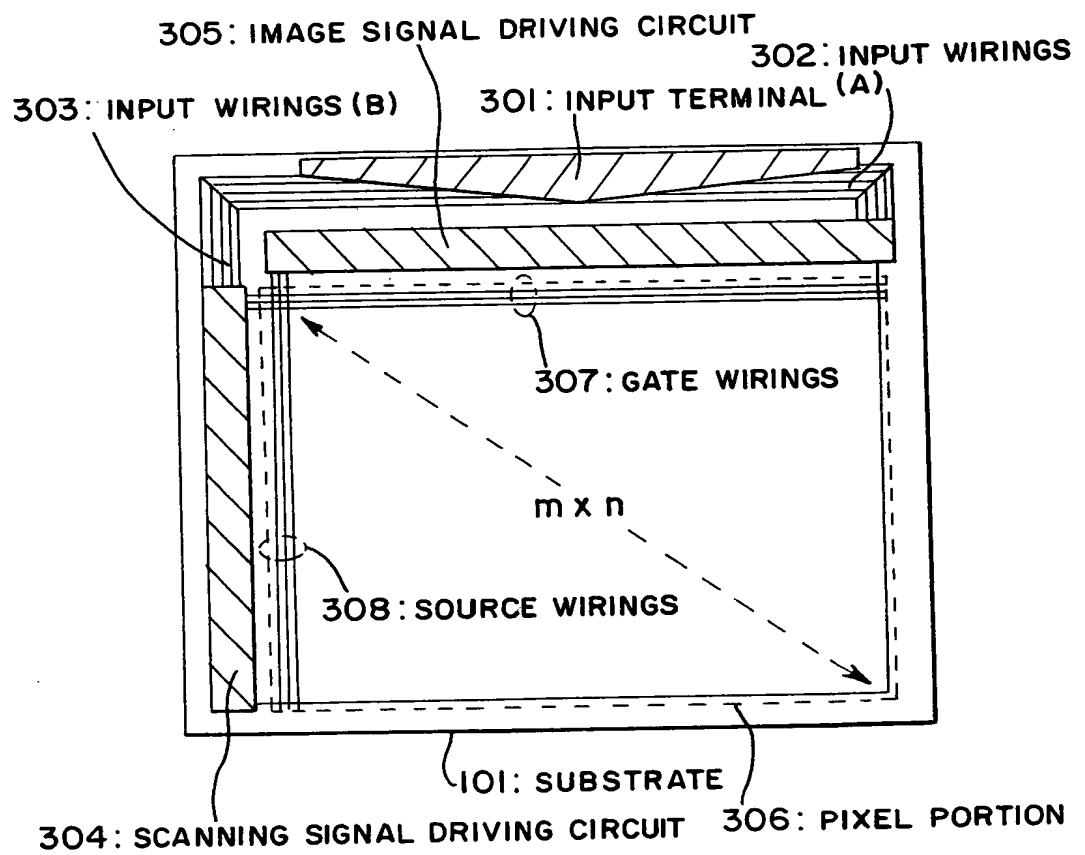


FIG. 11

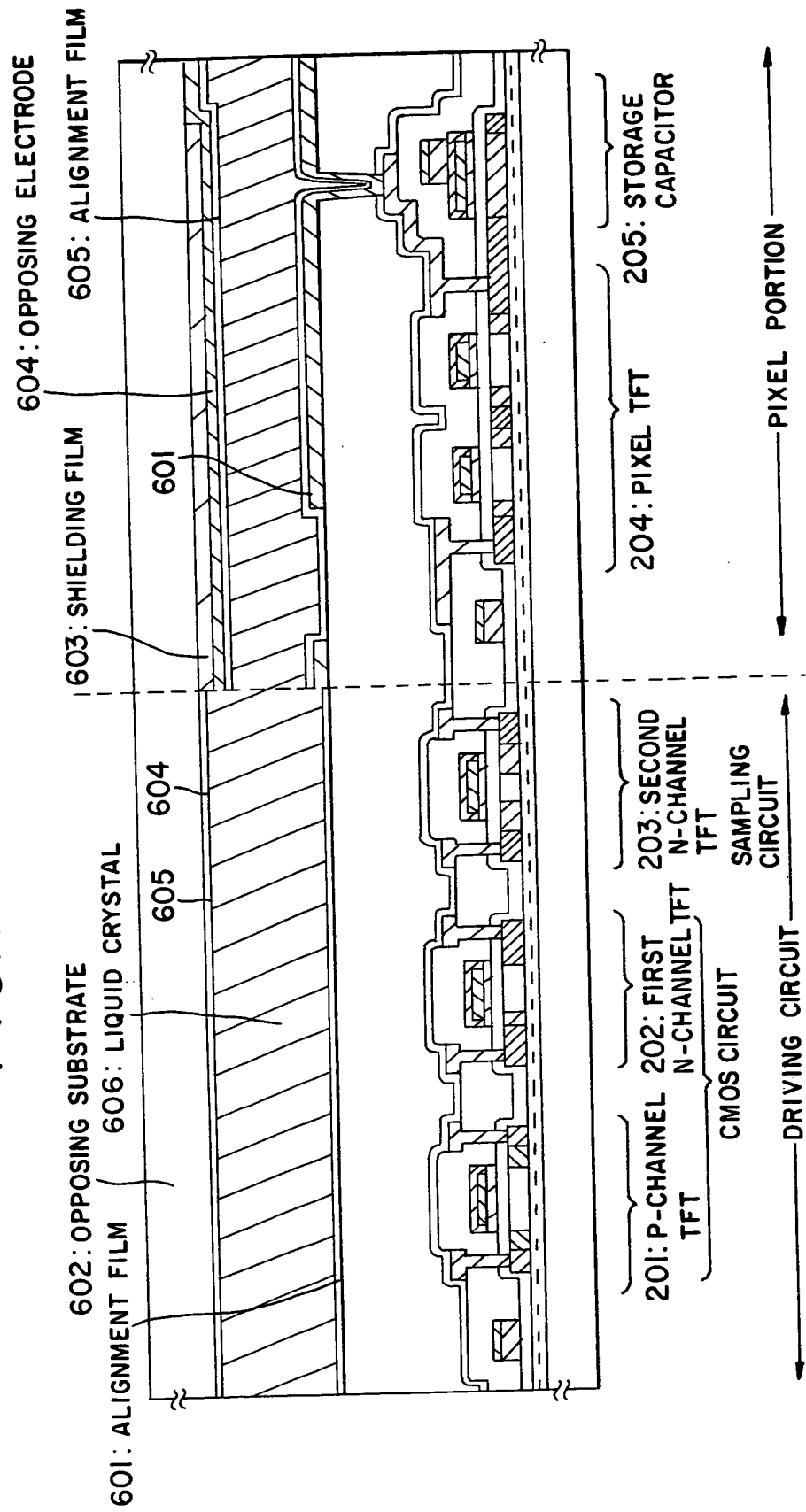


FIG. 12

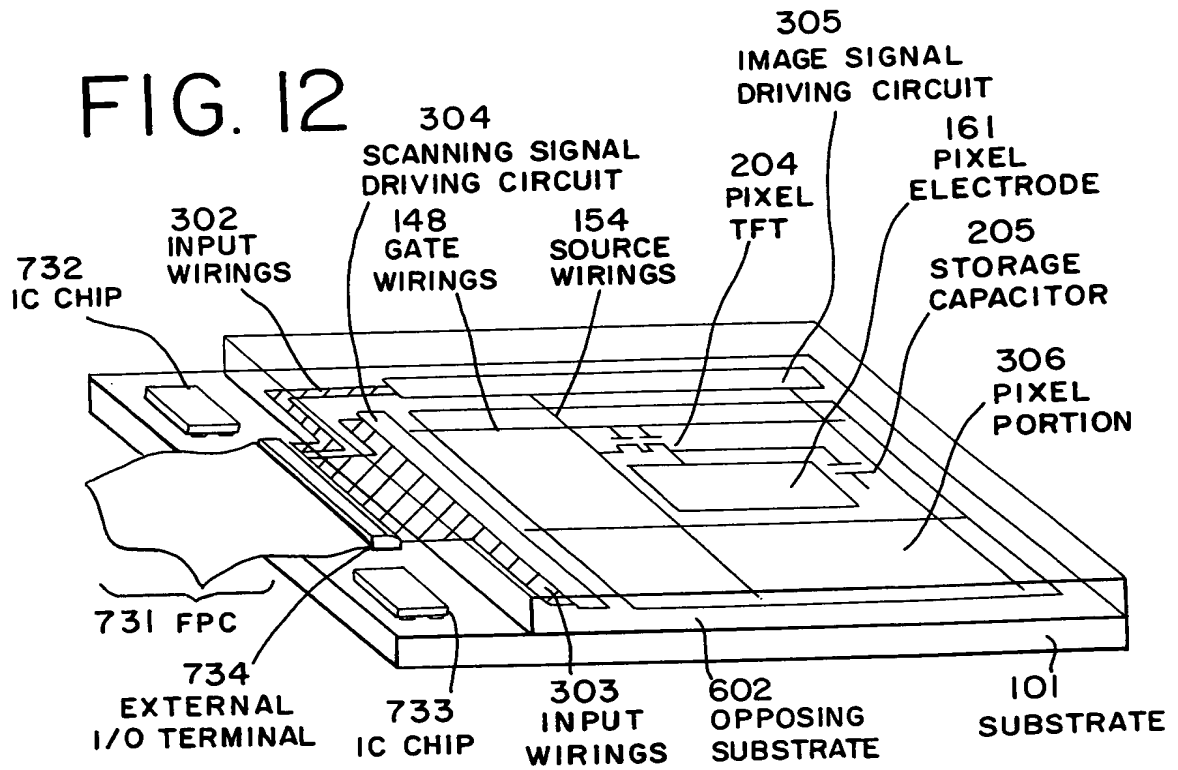


FIG. 13

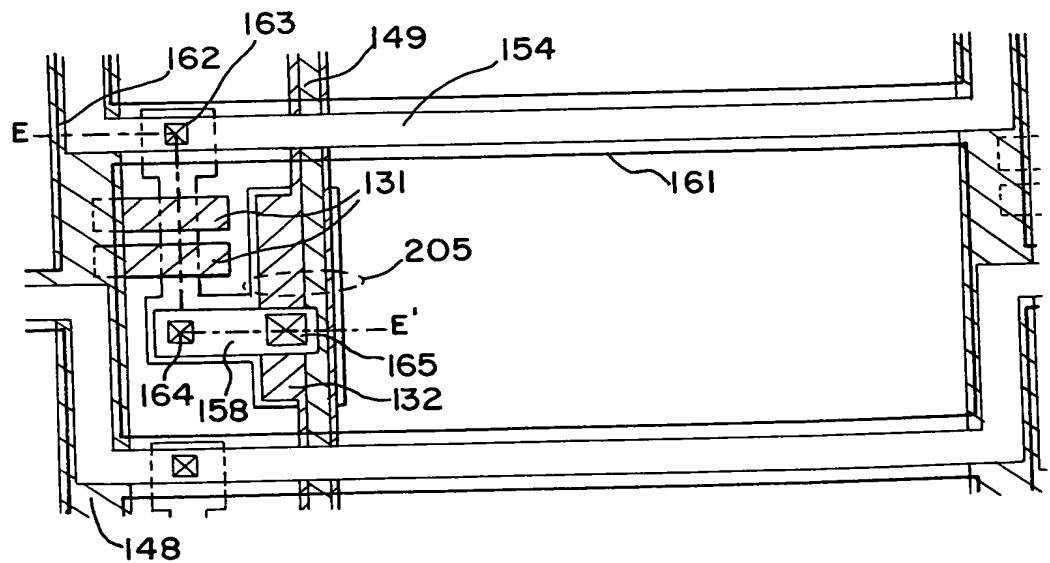


FIG.14

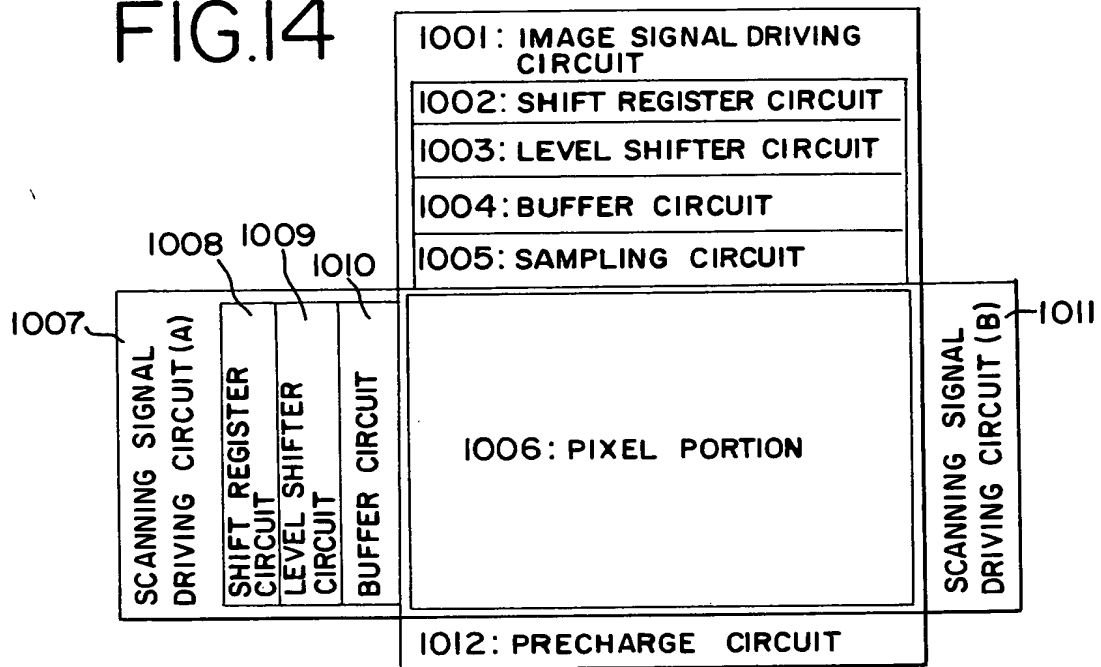


FIG.15(A)

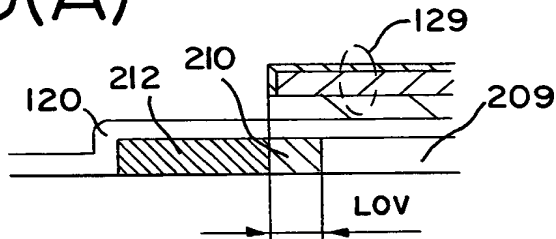


FIG.15(B)

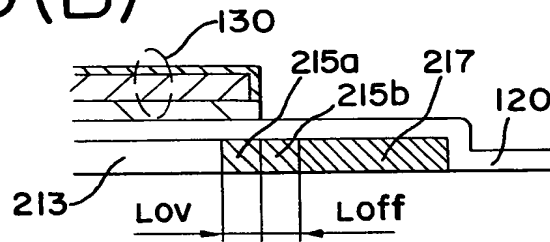


FIG.15(C)

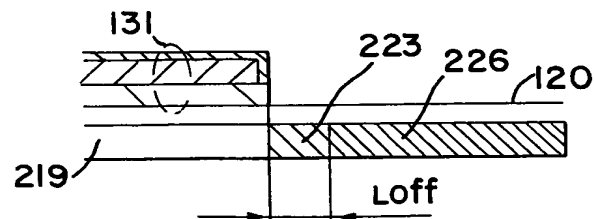


FIG.16(A)

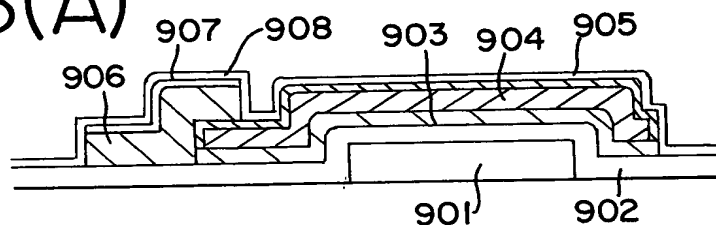


FIG.16(B)

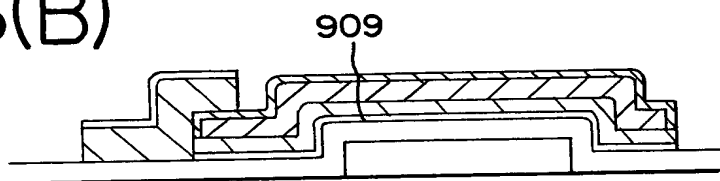


FIG.16(C)

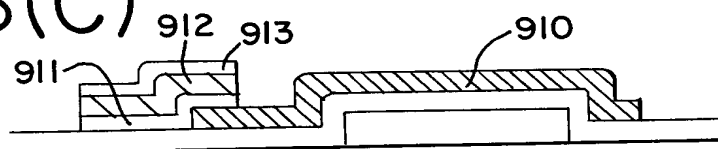


FIG.17(A)

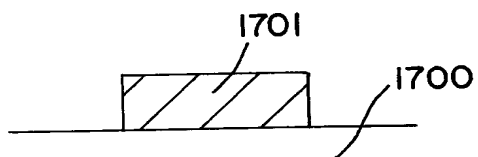


FIG.17(D)

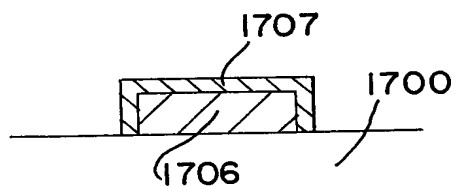


FIG.17(B)

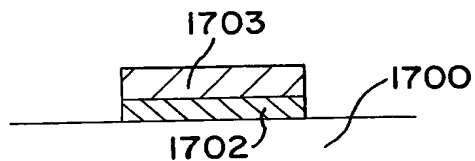


FIG.17(E)

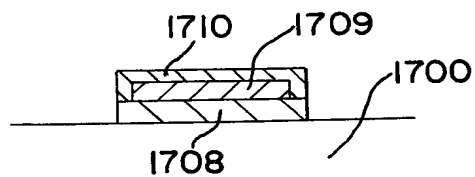


FIG.17(C)

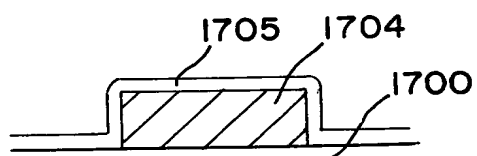


FIG.17(F)

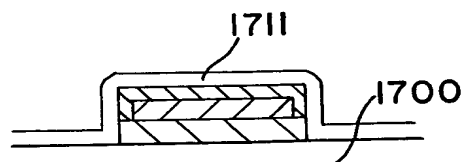


FIG. 18

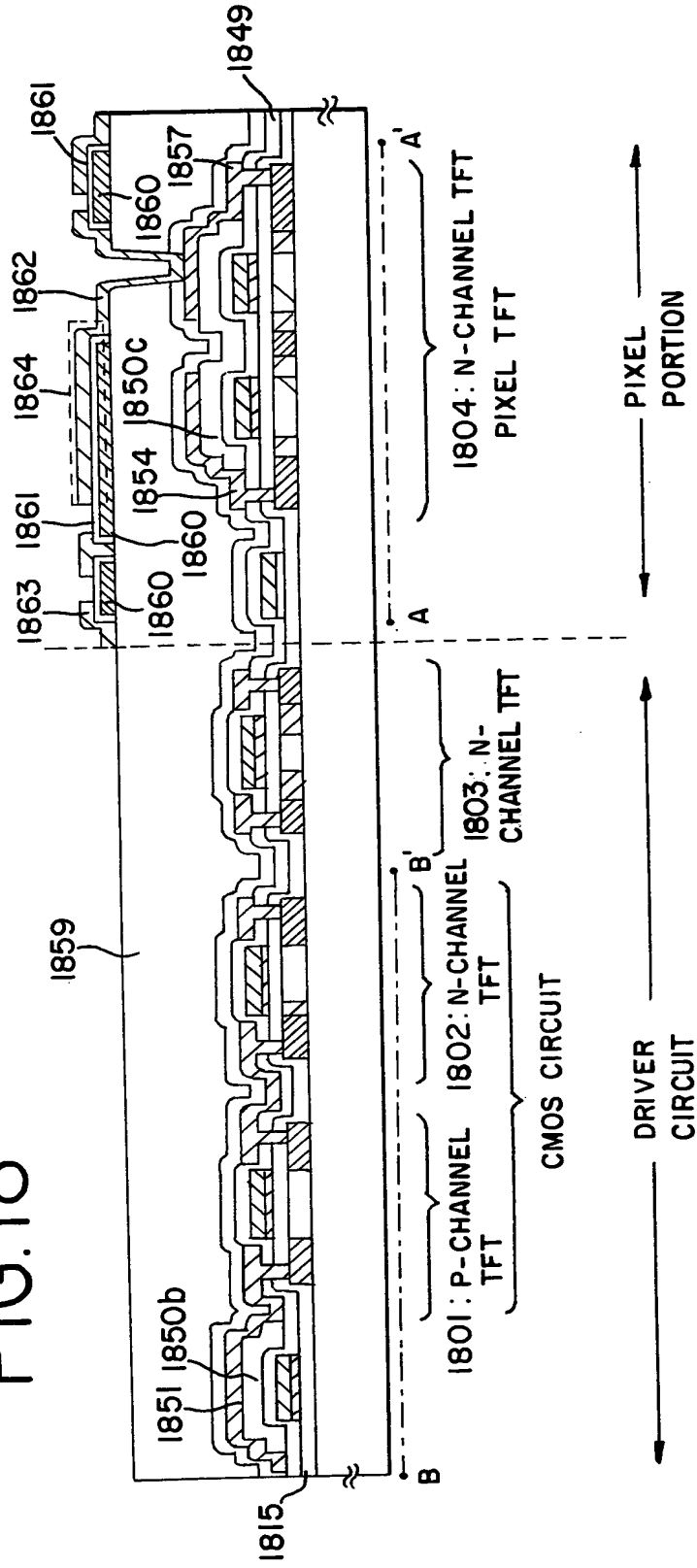


FIG.19(A)

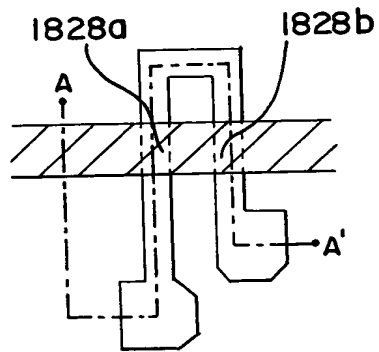


FIG.19(B)

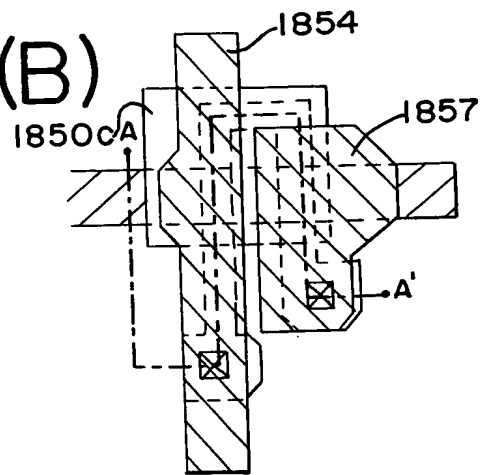


FIG.20(A)

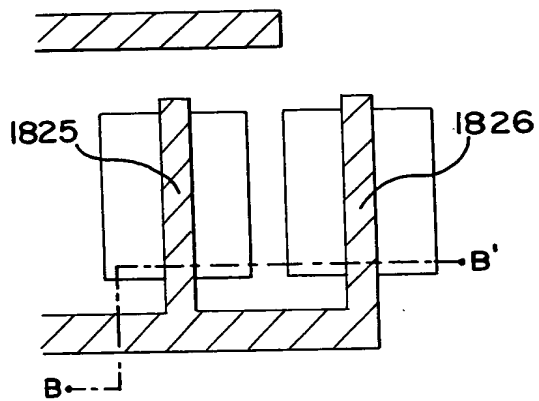


FIG.20(B)

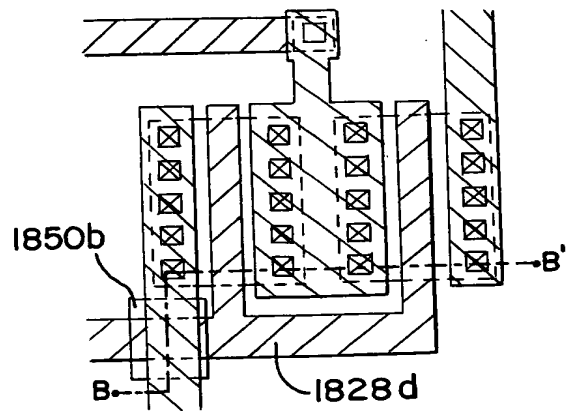


FIG.21

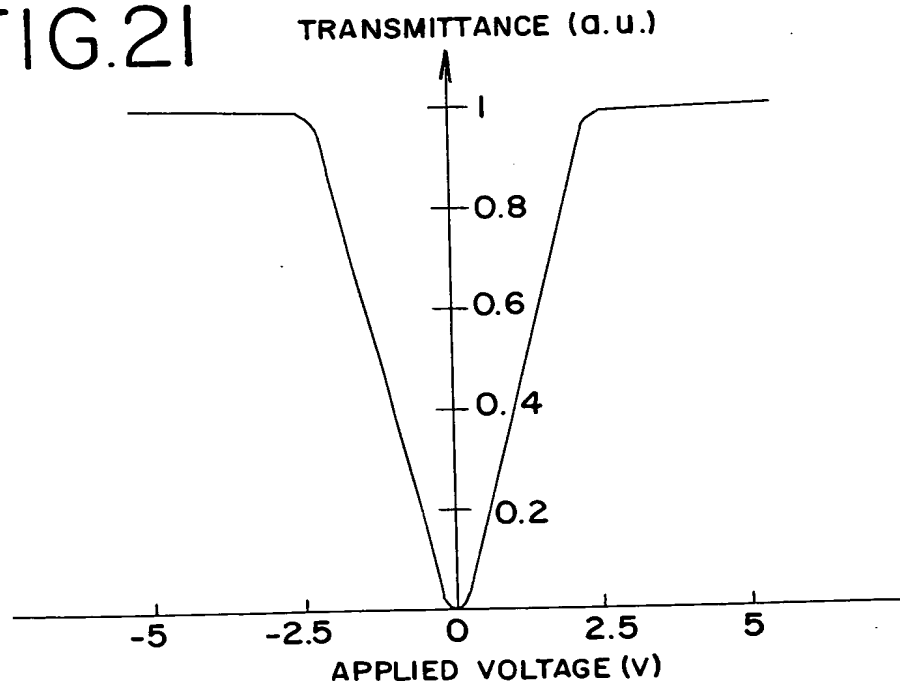


FIG.23(A)

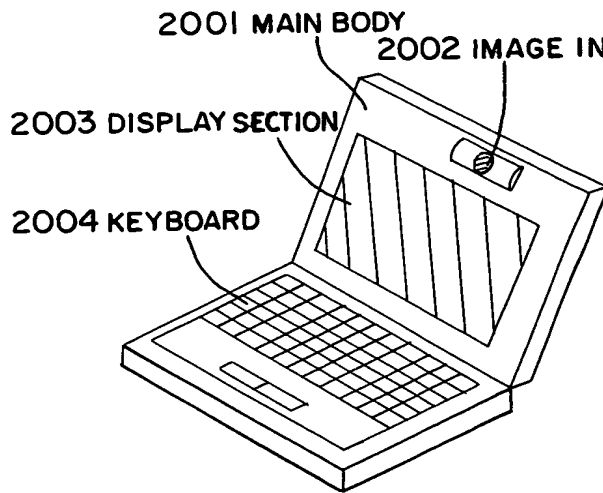


FIG.23(B)

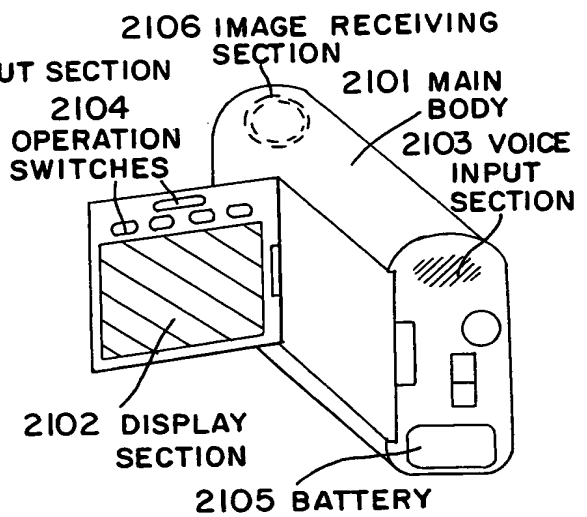


FIG.23(C)

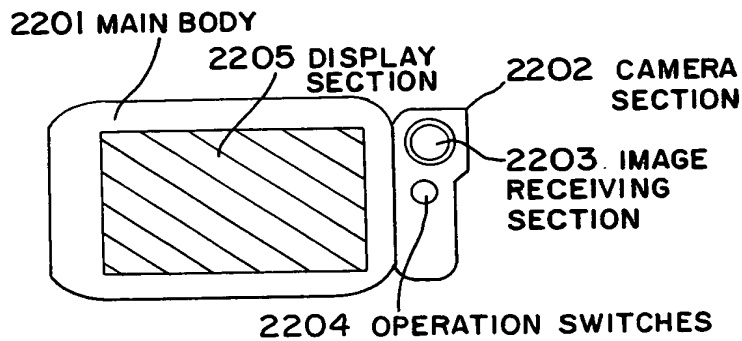


FIG.23(D)

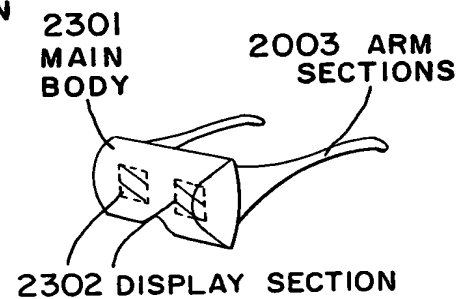


FIG. 23(E)

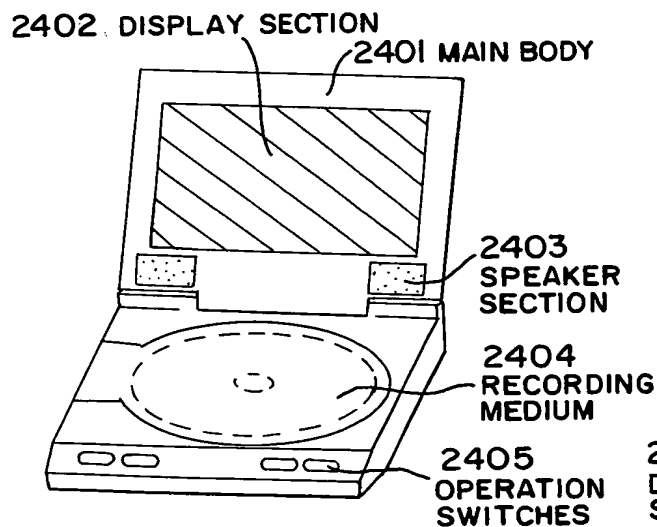


FIG.23(F)

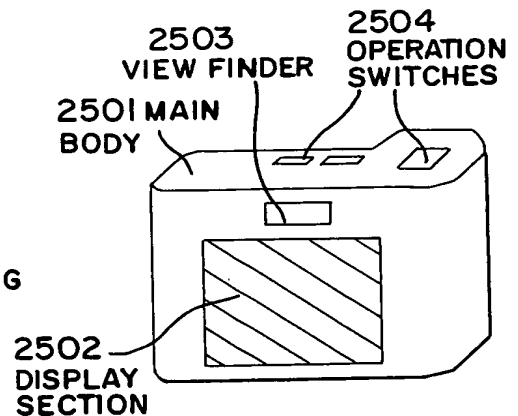


FIG.24(A)

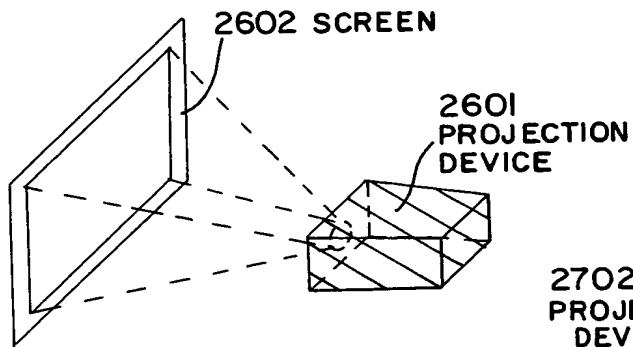


FIG.24(B)

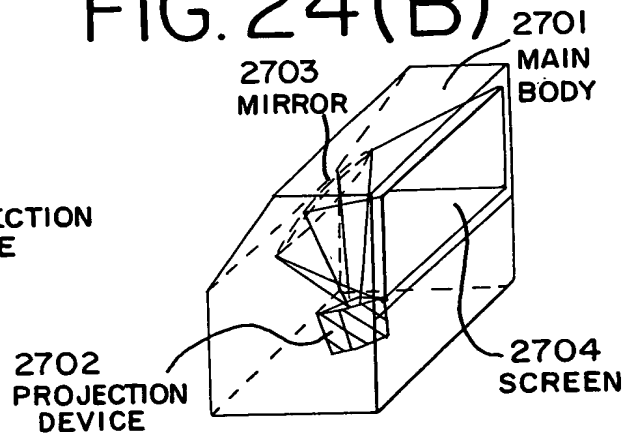


FIG.24(C) PROJECTION DEVICE (THREE-PLATE STYLE) TOWARD SCREEN

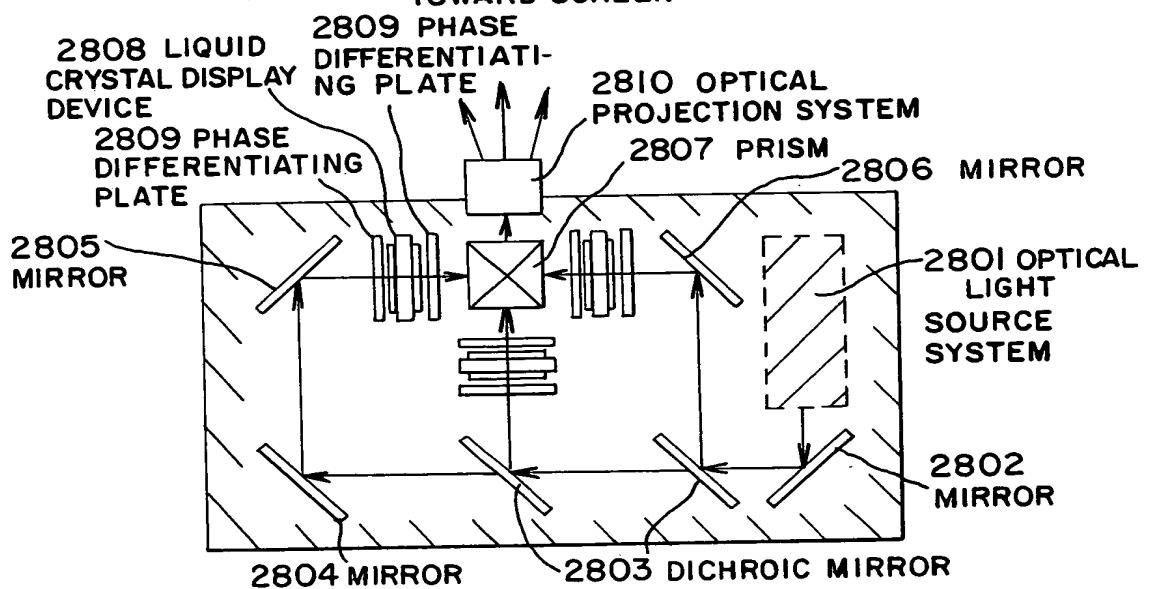


FIG.24(D) OPTICAL LIGHT SOURCE SYSTEM

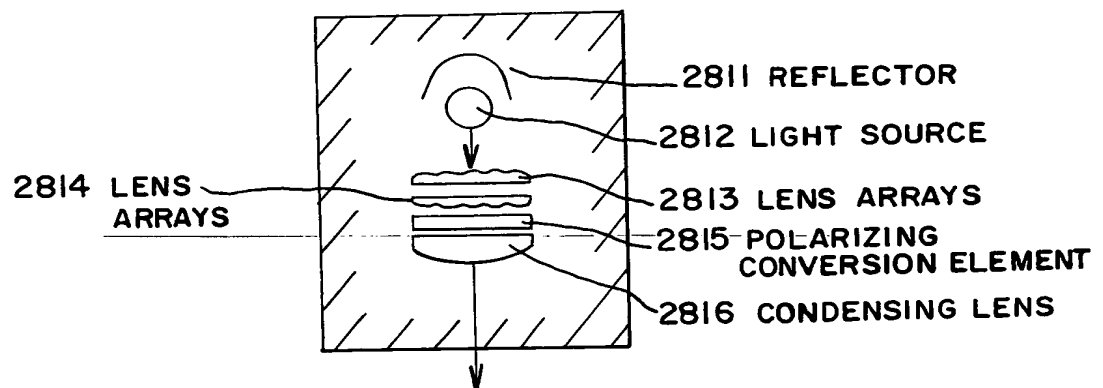


FIG.25

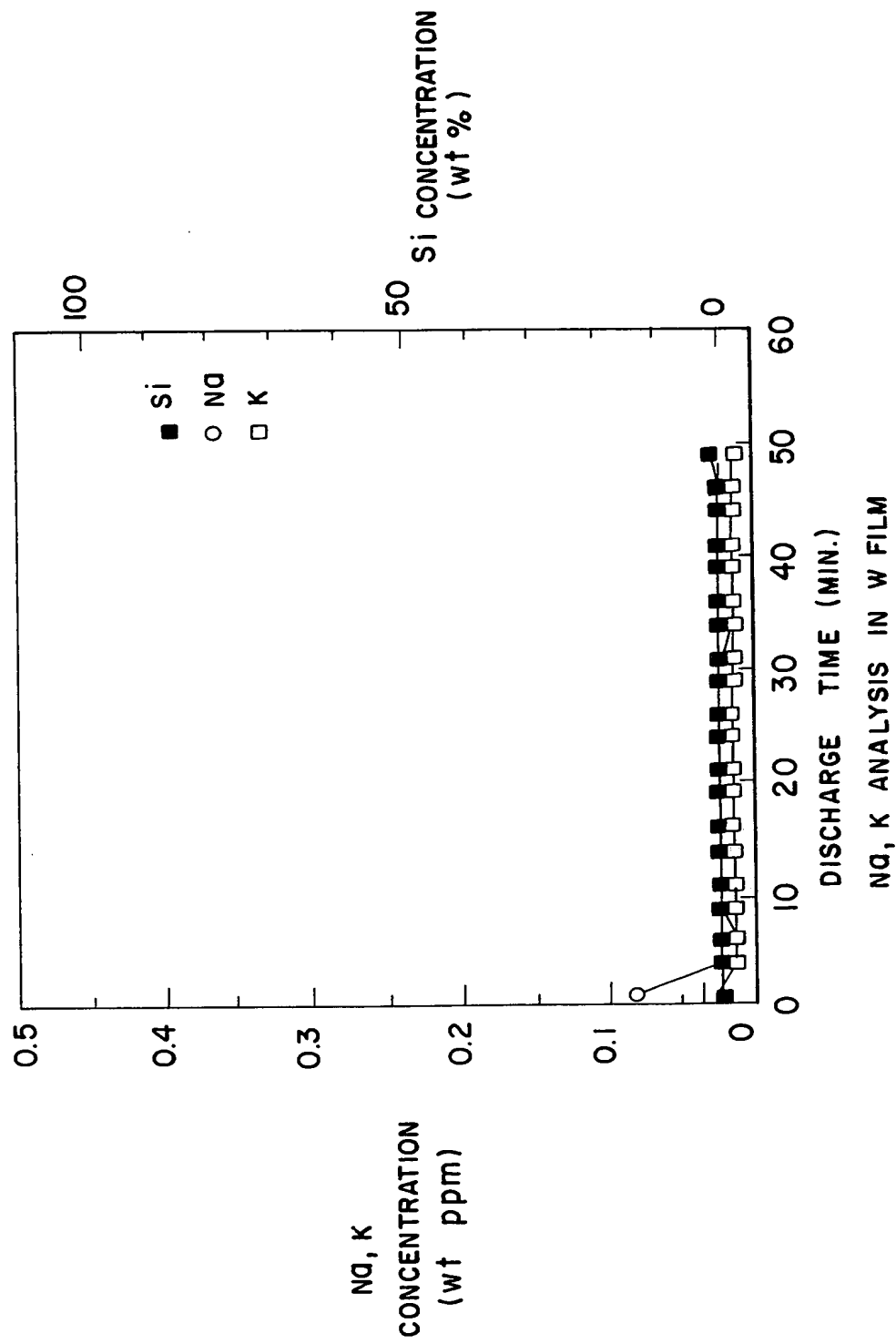


FIG.26(A)

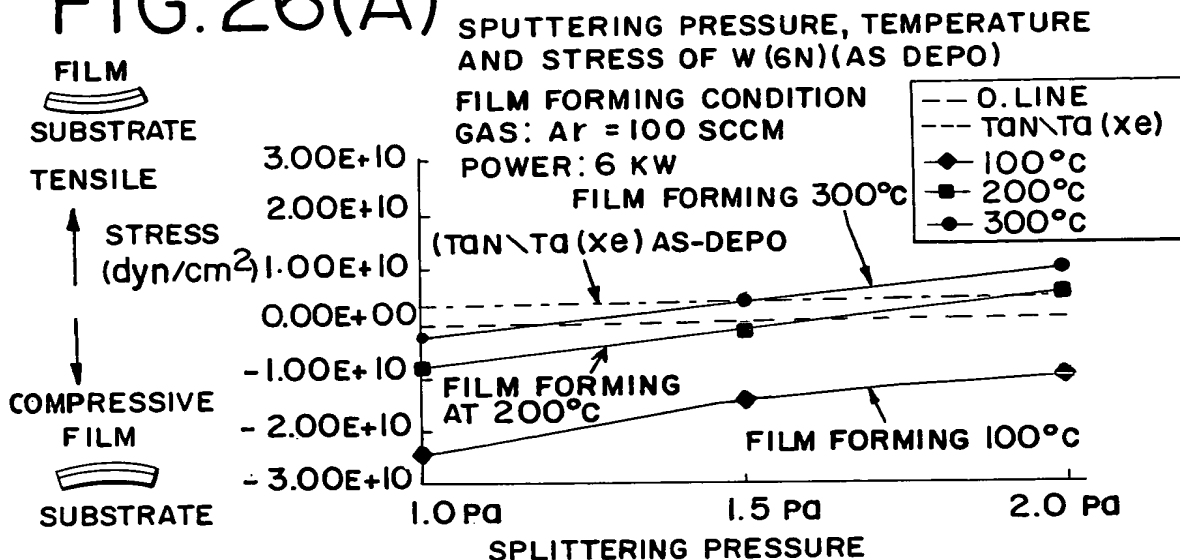


FIG.26(B)

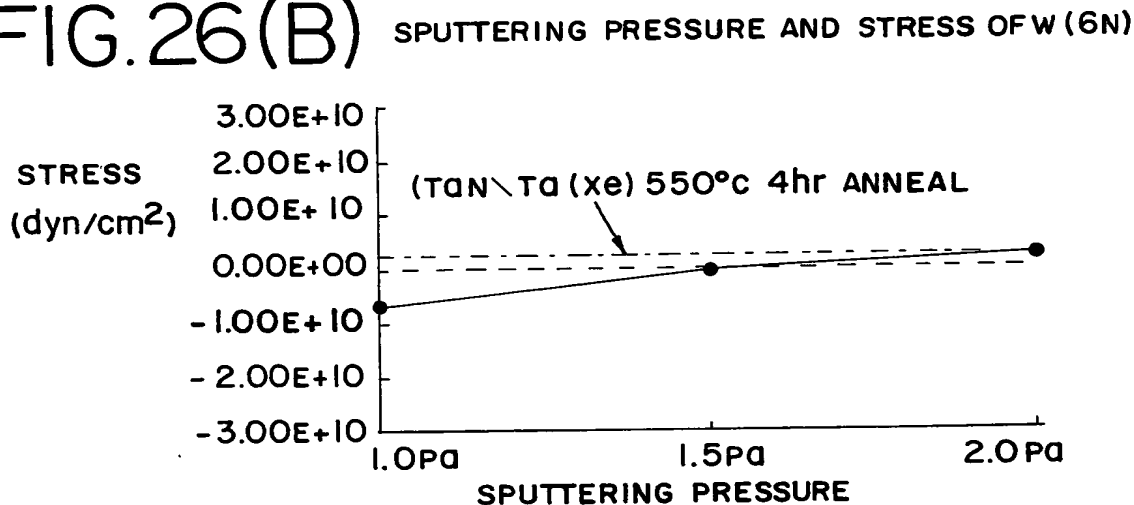


FIG.26(C)

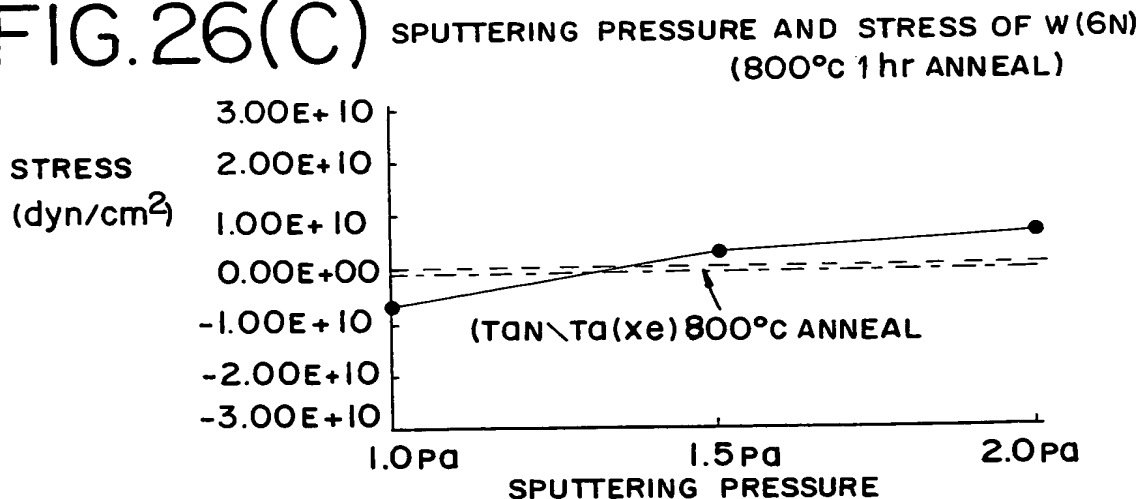


FIG.27(A)

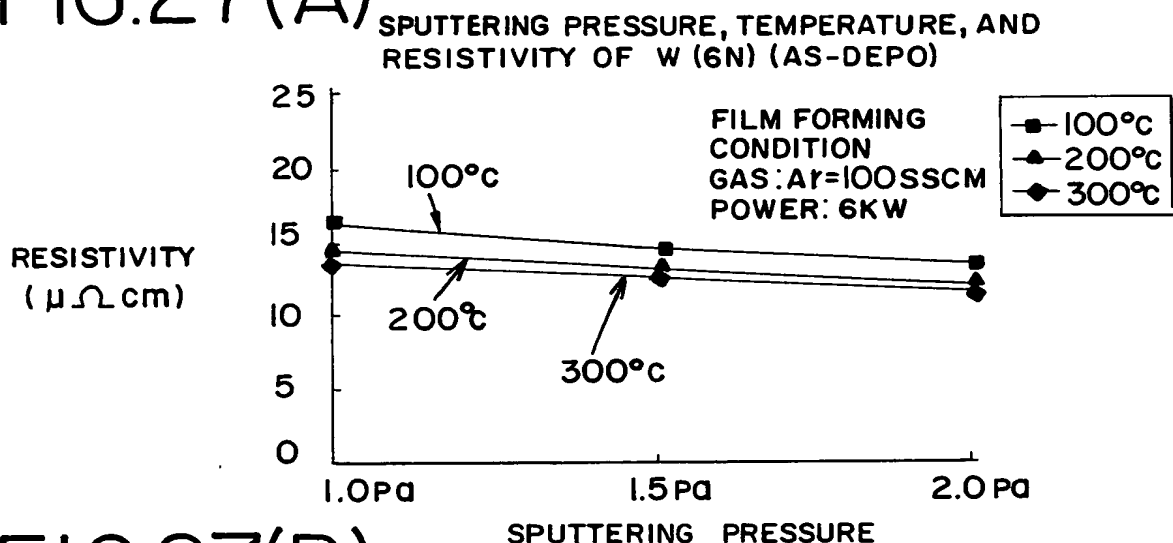


FIG.27(B)

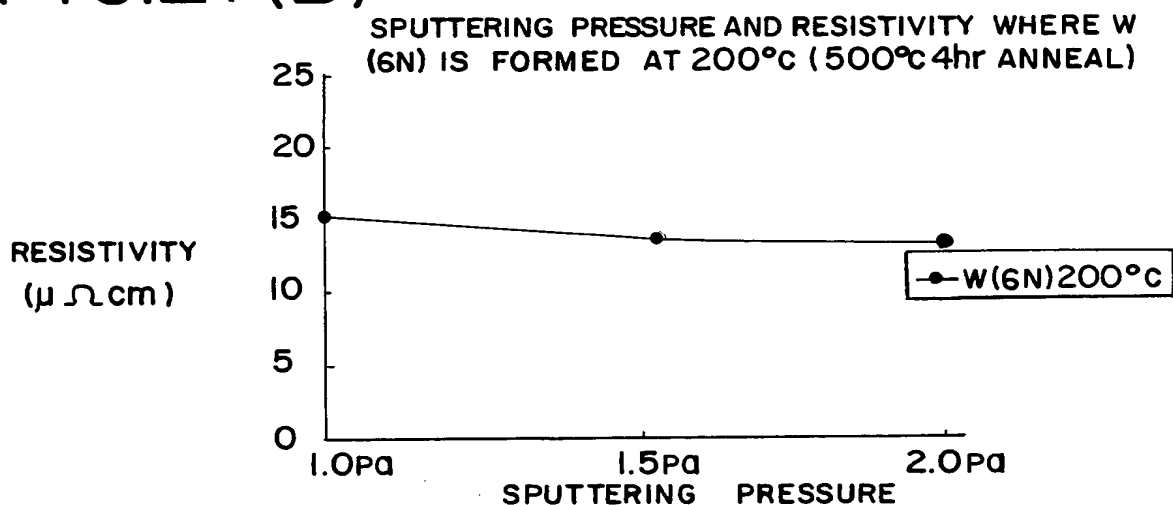


FIG.27(C)

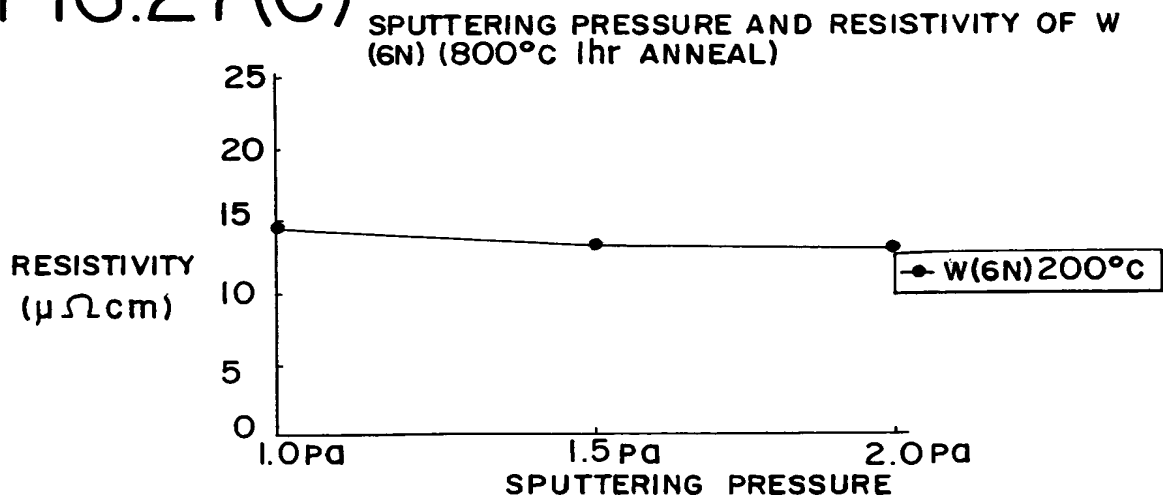


FIG.28(A) TENSILE STRESS

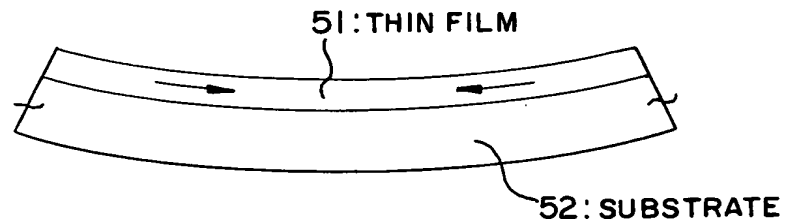


FIG.28(B)

COMPRESSIVE STRESS

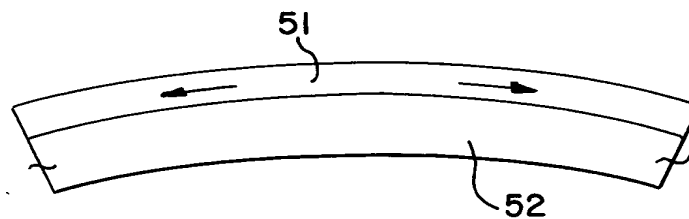


FIG. 29

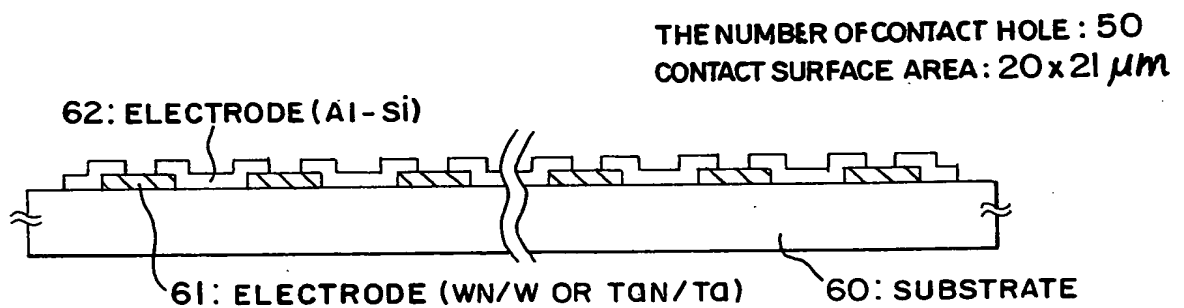


FIG.30

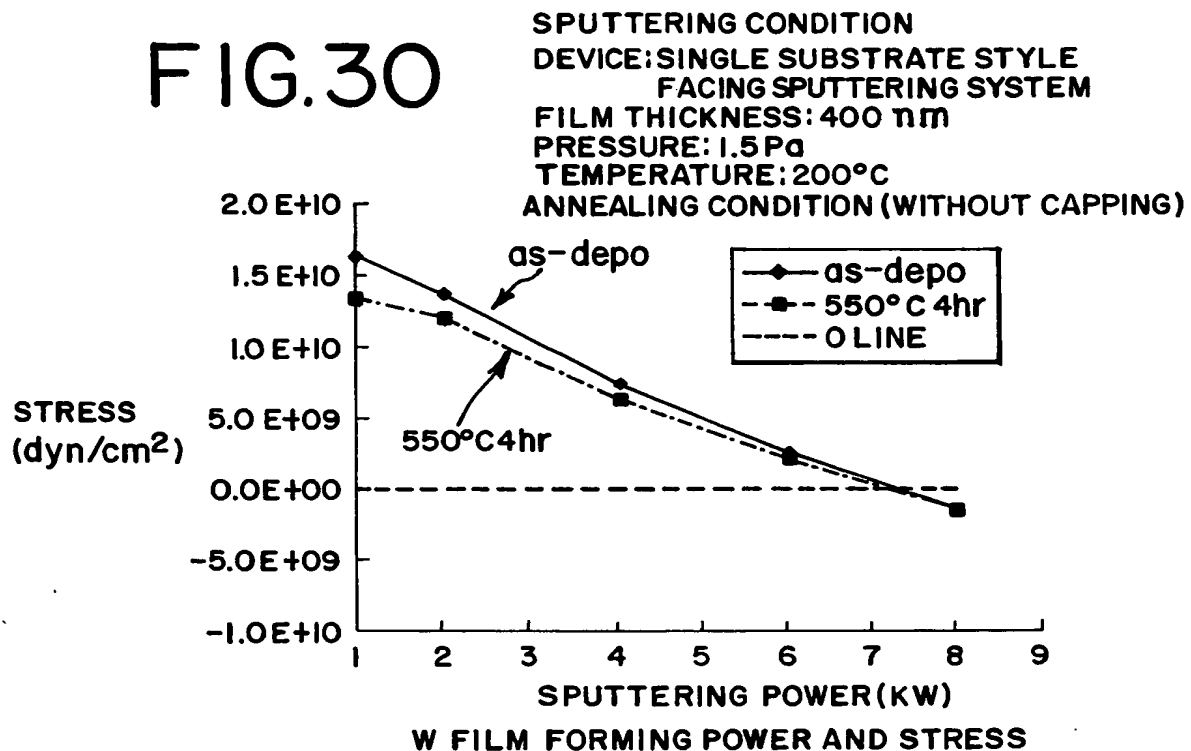


FIG.31

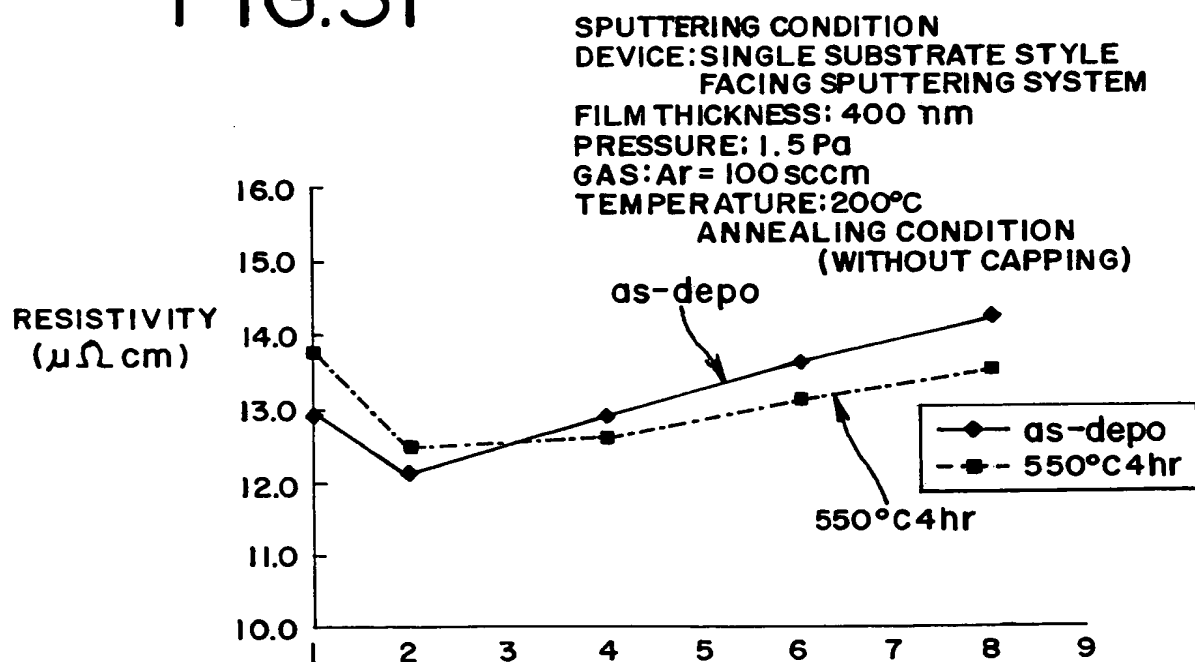


FIG.32

